

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
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EPAS ID: PAT3370953

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	RELEASE OF SECURITY INTEREST
CONVEYING PARTY DATA	
Name	Execution Date
TEXAS CAPITAL BANK, N.A., AS ADMINISTRATIVE AGENT	11/04/2014
RECEIVING PARTY DATA	
Name:	PREMIX, INC.
Street Address:	3365 EAST CENTER STREET
City:	NORTH KINGSVILLE
State/Country:	OHIO
Postal Code:	44068
PROPERTY NUMBERS Total: 13	
Property Type	Number
Patent Number:	5744816
Patent Number:	6040391
Patent Number:	6365069
Patent Number:	7359629
Patent Number:	8058324
Patent Number:	5854317
Patent Number:	6251308
Patent Number:	6752937
Patent Number:	7579574
Patent Number:	5998510
Patent Number:	6436315
Patent Number:	7170038
Patent Number:	8487040
CORRESPONDENCE DATA	
Fax Number:	(212)446-4900
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
Email:	susan.zablocki@kirkland.com
Correspondent Name:	SUSAN ZABLOCKI
Address Line 1:	KIRKLAND & ELLIS LLP
Address Line 2:	601 LEXINGTON AVENUE

PATENT

Address Line 4: NEW YORK, NEW YORK 10022	
ATTORNEY DOCKET NUMBER:	22783-43
NAME OF SUBMITTER:	SUSAN ZABLOCKI
SIGNATURE:	/susan zablocki/
DATE SIGNED:	05/27/2015
Total Attachments: 4 source=citadel - IPSA (2014) - Release of Security Interest in IP re Premix (Pa (2)#page1.tif source=citadel - IPSA (2014) - Release of Security Interest in IP re Premix (Pa (2)#page2.tif source=citadel - IPSA (2014) - Release of Security Interest in IP re Premix (Pa (2)#page3.tif source=citadel - IPSA (2014) - Release of Security Interest in IP re Premix (Pa (2)#page4.tif	

RELEASE OF SECURITY INTEREST IN INTELLECTUAL PROPERTY

THIS RELEASE OF SECURITY INTEREST IN INTELLECTUAL PROPERTY (this "Release") is made as of November 4, 2014 ("Effective Date") by **TEXAS CAPITAL BANK, N.A.**, in its capacity as Administrative Agent, with its principal office at 2000 McKinney Avenue, Suite 700, Dallas, Texas 75201 ("Secured Party"), in favor of **PREMIX, INC.**, an Ohio corporation, with its principal office at 3365 East Center St, North Kingsville, OH 44068 ("Debtor").

WHEREAS, pursuant to the terms and conditions of that certain Intellectual Property Security Agreement by and between Debtor and Secured Party dated December 30, 2010 (the "Agreement"), Debtor granted to Secured Party, for itself and on behalf of and for the ratable benefit of the other Secured Creditors, a continuing security interest in and to all of Debtor's right, title and interest in, to and under all of the Collateral, as described therein, (collectively, the "Collateral"), including, without limitation, the United States Trademarks, together with the goodwill associated therewith, and Patents set forth on Schedules A and B attached hereto;

WHEREAS, Debtor and Secured Party entered into the Agreement pursuant to the terms and conditions of that certain Security Agreement by and between Debtor and Secured Party dated December 30, 2010 (the "Security Agreement");

WHEREAS, the Agreement was recorded with the United States Patent and Trademark Office ("PTO") on January 25, 2011, at Reel/Frame 4460/0317 and Reel/Frame 025692/0922; and

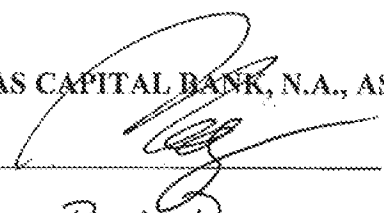
WHEREAS, Debtor has paid all of its outstanding indebtedness to Secured Party.

NOW, THEREFORE, for good and valuable consideration, the receipt and sufficiency of which are hereby acknowledged, Secured Party hereby terminates the Agreement and the Security Agreement, and hereby terminates, cancels and releases any and all security interests it has against the Collateral.

Secured Party shall, at Debtor's expense, take all further actions, and provide to Debtor, Debtor's successors, assigns or other legal representatives, all such cooperation and assistance (including, without limitation, the execution and delivery of any and all documents or other instruments), requested by Debtor to more fully and effectively effectuate the purposes of this Release.

* * * * *

IN WITNESS WHEREOF, Secured Party has caused this Release to be executed by its duly authorized representative effective as of the Effective Date.


TEXAS CAPITAL BANK, N.A., AS ADMINISTRATIVE AGENT

Name: Ricki Roberts

Title: Executive Vice President

SCHEDULE A

U.S. TRADEMARKS

1	Serial #: 72381535 Mark: PREMI-GLAS	Filing Dt: 01/21/1971	Reg #: 933714	Reg. Dt: 05/16/1972
2	Serial #: 73167042 Mark: PREMI-JECT	Filing Dt: 04/19/1978	Reg #: 1125099	Reg. Dt: 09/18/1979
3	Serial #: 73211472 Mark: PREMIX	Filing Dt: 04/13/1979	Reg #: 1253245	Reg. Dt: 10/04/1983
4	Serial #: 73420850 Mark: QVENAL	Filing Dt: 04/11/1983	Reg #: 1297607	Reg. Dt: 09/25/1984
5	Serial #: 73494562 Mark: TMC	Filing Dt: 06/11/1984	Reg #: 1335935	Reg. Dt: 05/14/1985
6	Serial #: 73586805 Mark: PREMIX	Filing Dt: 03/07/1986	Reg #: 1425746	Reg. Dt: 01/20/1987
7	Serial #: 73829082 Mark: PREMIX	Filing Dt: 10/02/1989	Reg #: 1626775	Reg. Dt: 12/11/1990
8	Serial #: 74669441 Mark: AMC	Filing Dt: 05/03/1995	Reg #: 2056049	Reg. Dt: 04/22/1997
9	Serial #: 75592460 Mark: OPTORR	Filing Dt: 11/20/1998	Reg #: 2300007	Reg. Dt: 12/14/1999
10	Serial #: 77678900 Mark: PREMI-GLAS 2550	Filing Dt: 02/26/2009	Reg #: 3865220	Reg. Dt: 10/19/2010

SCHEDULE B

U.S. PATENTS

- 1 Patent #: 5744816 Issue Dt: 04/28/1998 Application #: 08707752 Filing Dt: 09/04/1996
Title: LOW PRESSURE SHEET MOLDING COMPOUNDS
- 2 Patent #: 5854317 Issue Dt: 12/29/1998 Application #: 08769454 Filing Dt: 12/18/1996
Title: PROCESS FOR THICKENING THERMOSET RESIN MOLDING COMPOUND COMPOSITIONS
- 3 Patent #: 5998510 Issue Dt: 12/07/1999 Application #: 09016822 Filing Dt: 01/30/1998
Title: LOW PRESSURE SHEET MOLDING COMPOUNDS
- 4 Patent #: 6040391 Issue Dt: 03/21/2000 Application #: 09141931 Filing Dt: 08/28/1998
Title: PROCESS FOR THICKENING THERMOSET RESIN MOLDING COMPOUND COMPOSITIONS
- 5 Patent #: 6251308 Issue Dt: 06/26/2001 Application #: 09526641 Filing Dt: 03/16/2000
Title: Highly conductive molding compounds and fuel cell bipolar plates comprising these compounds
- 6 Patent #: 6436315 Issue Dt: 08/20/2002 Application #: 09849629 Filing Dt: 05/04/2001
Publication #: US20010049046 Pub Dt: 12/06/2001
Title: HIGHLY CONDUCTIVE MOLDING COMPOUNDS FOR USE AS FUEL CELL PLATES AND THE RESULTING PRODUCTS
- 7 Patent #: 6365069 Issue Dt: 04/02/2002 Application #: 09879327 Filing Dt: 06/12/2001
Publication #: US20020005506 Pub Dt: 01/17/2002
Title: Process of injection molding highly conductive molding compounds and an apparatus for this process
- 8 Patent #: 6752937 Issue Dt: 06/22/2004 Application #: 10135955 Filing Dt: 04/29/2002
Publication #: US20030169638 Pub Dt: 09/11/2003
Title: HIGHLY CONDUCTIVE MOLDING COMPOUNDS HAVING AN INCREASED DISTRIBUTION OF LARGE SIZE GRAPHITE PARTICLES
- 9 Patent #: 7170038 Issue Dt: 01/30/2007 Application #: 11114703 Filing Dt: 04/26/2005
Publication #: US20050250397 Pub Dt: 11/10/2005
Title: MOLDING COMPOUNDS FOR USE IN INDUCTION HEATING APPLICATIONS AND HEATING ELEMENTS MOLDED FROM THESE COMPOUNDS
- 10 Patent #: 7359629 Issue Dt: 04/15/2008 Application #: 11114833 Filing Dt: 04/26/2005
Publication #: US20060193722 Pub Dt: 08/31/2006
Title: MOLDING COMPOUNDS FOR USE IN FURNACE BLOWER HOUSINGS AND BLOWER HOUSINGS MOLDED FROM THESE COMPOUNDS
- 11 Patent #: 7579574 Issue Dt: 08/25/2009 Application #: 11644533 Filing Dt: 12/22/2006
Publication #: US20070106001 Pub Dt: 05/10/2007
Title: MOLDING COMPOUNDS FOR USE IN INDUCTION HEATING APPLICATIONS AND HEATING ELEMENTS MOLDED FROM THESE COMPOUNDS
- 12 Patent #: 8487040 Issue Dt: 07/16/2013 Application #: 11980275 Filing Dt: 10/30/2007
Publication #: US20090111927 Pub Dt: 04/30/2009
Title: FLAME AND SMOKE SPREAD RETARDANT MOLDING COMPOUNDS AND COMPONENTS MOLDED FROM THESE COMPOUNDS
- 13 Patent #: 8058324 Issue Dt: 11/15/2011 Application #: 12217744 Filing Dt: 07/08/2008
Publication #: US20090111908 Pub Dt: 04/30/2009
Title: ANTIMICROBIAL FLAME AND SMOKE SPREAD RETARDANT MOLDING COMPOUNDS AND COMPONENTS MOLDED FROM THESE COMPOUNDS